RELIABILITY REPORT

FOR

MAX4852ETE+
(MAX4850/MAX4850H/MAX4852/MAX4852H)

PLASTIC ENCAPSULATED DEVICES

January 22, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

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Approved by
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Quality Assurance
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Conclusion

The MAX4852ETE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4850/MAX4850H/MAX4852/MAX4852H family of dual SPDT (single-pole/double-throw) switches operate from a single +2V to +5.5V supply and can handle signals greater than the supply rail. These switches feature low 3.5 or 3.5 /7 on-resistance with low on-capacitance, making them ideal for switching audio and data signals. The MAX4850/MAX4850H are configured with two SPDT switches and feature two comparators for headphone detection or mute/send key functions. The MAX4852 has two SPDT switches with no comparators for low 1µA supply current. For over-rail applications, these devices offer either the pass-through or high-impedance option. For the MAX4850/MAX4852, the signal (up to 5.5V) passes through the switch without distortion even when the positive supply rail is exceeded. For the MAX4850H/MAX4852H, the switch input becomes high impedance when the input signal exceeds the supply rail. The MAX4850/MAX4850H/MAX4852/MAX4852H are available in the space-saving (3mm x 3mm), 16-pin TQFN package and operate over the extended temperature range of -40°C to +85°C.

II. Manufacturing Information

A. Description/Function:	Dual SPDT Analog Switches with Over-Rail Signal Handling
B. Process:	TSMC 0.5µm Silicon Gate CMOS
C. Number of Device Transistors:	
D. Fabrication Location:	Taiwan
E. Assembly Location:	ISPL Philippines, ASAT China, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	July 24, 2004

III. Packaging Information

A. Package Type:	16-pin TQFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1261
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	64°C/W
K. Single Layer Theta Jc:	6.9°C/W
L. Multi Layer Theta Ja:	48°C/W
M. Multi Layer Theta Jc:	6.9°C/W

IV. Die Information

A. Dimensions:	61 X 61 mils
B. Passivation:	SiO_2 (Oxide)/Si_3N_4 (Nitride)
C. Interconnect:	Al/Cu (0.5%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.5um
F. Minimum Metal Spacing:	0.5um
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	Silicon dioxide
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the TSMC 0.5um Process results in a FIT Rate of 4.5 @ 25C and 77.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AS40-5 die type has been found to have all pins able to withstand a HBM transient pulse of +/-200 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4852ETE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data